

Product	Laser diode
Package	RLD90QZW5

Materials	Flow chart			Name of process	Used equipment & machine	Controlled item
	Material acceptance	Preparatory process	Main Process			
LD chip	<pre> graph TD A[Material acceptance] --> B{1} B --> C((2)) C --> D{3} D --> E((4)) E --> F((5)) F --> G((6)) G --> H{7} H --> I((8)) I --> J{9} </pre>			Acceptance test	Visual	Appearance
Submount				Chips preparation	Braking machine Expander	Appearance Air pressure Temperature
				Acceptance test	Microscope	Appearance
				Die-&wire-bonding(1)	ALDW40	Temperature DB load Ultrasonic power WB load
Stem						
Ag paste						
				Inspection(0)		DB position Wire-pull resistivity
Bondhing agent						Peel-off resistivity
				Die-&wire-bonding	ASDW	Temperature DB load Ultrasonic power
	Inspection	Microscope Tension gauge FFP standard Correct monitorscope	Wire-pull resistivity DB load Facet inclination △XYZ			

Materials	Flow chart			Name of process	Used equipment & machine	Controlled item
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Cap				Can sealing	AACL	Air pressure N2 pressure Humidity
				Inspection for sealing	Cutting nipper Micrometer Correct monitorscope	Weld strength Weld extrusion Degree of decentering
				Products burn-in test	AATB	Set temperature I-L characteristics (100% test)
				Final measurement① Marking	ATMS	Temperature I-V characteristics Positional Appearance (100% test)
				Final measurement②	APFT	Temperature I-L characteristics I-V characteristics FFP Wavelength
				Appearance check	Microscope	Crazing and dirt of lens Flaws of stem In deposition (100% test)
				Quantity treatment	Calculator	Quantity check
				Packing		Slip Indication check
				Shipment inspection		Outer label and contents check
				Packaging		Detailed statement for shipment Packing condition
				Shipment		

Notes

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